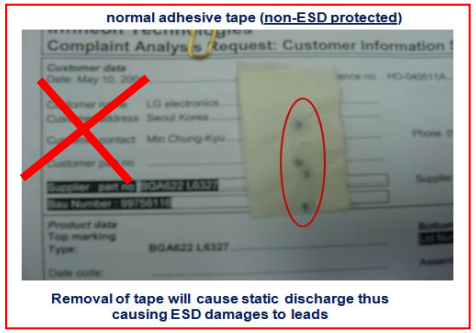
When sending components to the FA, several factors need to be taken into account to ensure a smooth and successful analysis process.

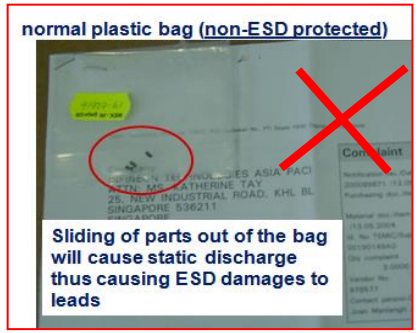
1. Contact your IFX counterpart first and register your concern: Do not sent back material without the IFX reference number. This allows IFX to direct the material to the most suitable FA-site, ensuring efficient support and processing.
2. Clear Labeling: Components must be clearly labeled with the provided reference by Infineon. Use one packing per returned sample, if applicable.
3. Proper Packaging: Components must be properly packaged to prevent damage during shipping. This includes using anti-static materials and avoiding mechanical stress especially to the leads.
4. Component Preparation: Make sure the IFX material is desoldered, reconditioned and in a testable state.

Example for proper ESD packaging for the devices to avoid component damage prior to analysis:



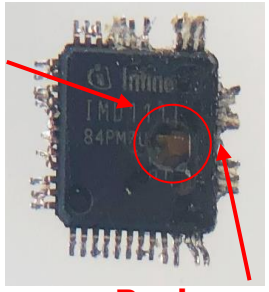






Example of untestable condition:

Serious burnt mark









This guideline is referring to JESD671a.

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